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74ALVCH16373

2.5 V/3.3 V 16-bit D-type transparent latch; 3-state

Rev. 6 — 10 July 2012 Product data sheet

1. General description

The 74ALVCH16373 is 16-bit D-type transparent latch featuring separate D-type inputs for each latch and 3-state outputs for bus oriented applications.

Incorporates bus hold data inputs which eliminate the need for external pull-up or pull-down resistors to hold unused inputs.

One latch enable (LE) input and one output enable ($\overline{OE}$) are provided per 8-bit section.

The 74ALVCH16373 consists of 2 sections of eight D-type transparent latches with 3-state true outputs. When LE is HIGH, data at the nDn inputs enter the latches. In this condition the latches are transparent, therefore a latch output will change each time its corresponding D-input changes.

When LE is LOW, the latches store the information that was present at the nDn inputs at a set-up time preceding the LOW-to-HIGH transition of LE. When $\overline{OE}$ is LOW, the contents of the eight latches are available at the outputs. When $\overline{OE}$ is HIGH, the outputs go to the high-impedance OFF-state. Operation of the $\overline{OE}$ input does not affect the state of the latches.

2. Features and benefits

- Wide supply voltage range from 1.2 V to 3.6 V
- Complies with JEDEC standard JESD8-B
- CMOS low power consumption
- MULTIBYTE flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and GND pins for minimum noise and ground bounce
- Direct interface with TTL levels
- All data inputs have bus hold
- Output drive capability 50 Ω transmission lines at 85 °C
- Current drive ±24 mA at V_{CC} = 3.0 V

3. Ordering information

Table 1. Ordering information

Type number	Temperature range	Package		
		Name	Description	Version
74ALVCH16373DL	−40 °C to +85 °C	SSOP48	plastic shrink small outline package; 48 leads; body width 7.5 mm	SOT370-1
74ALVCH16373DGG	−40 °C to +85 °C	TSSOP48	plastic thin shrink small outline package; 48 leads; body width 6.1 mm	SOT362-1

4. Functional diagram

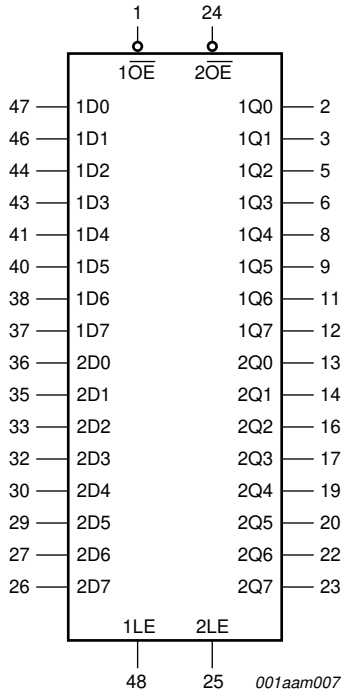


Fig 1. Logic symbol

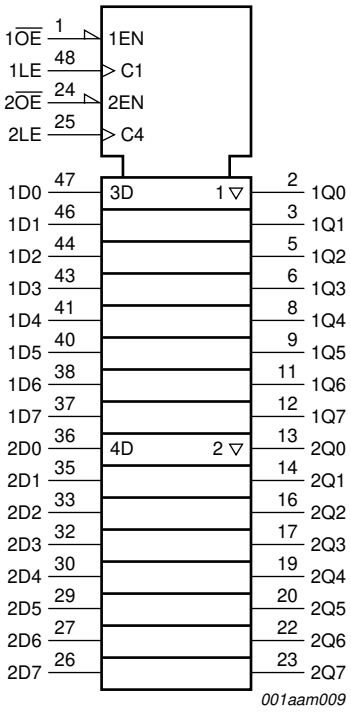


Fig 2. IEC logic symbol

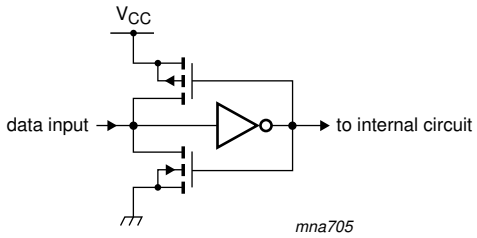


Fig 3. Bus hold circuit

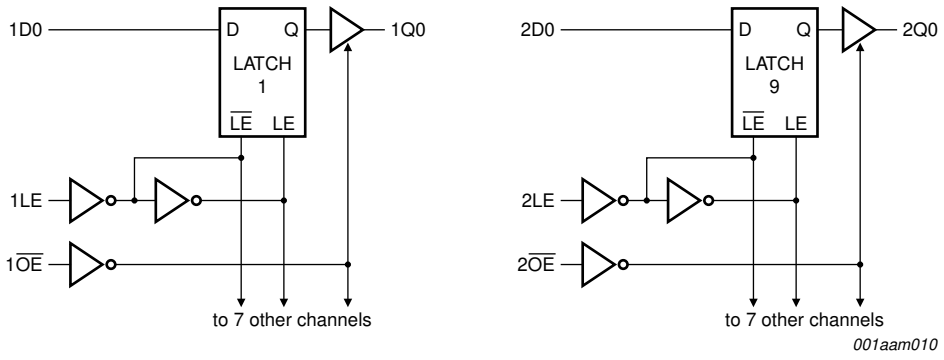


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning

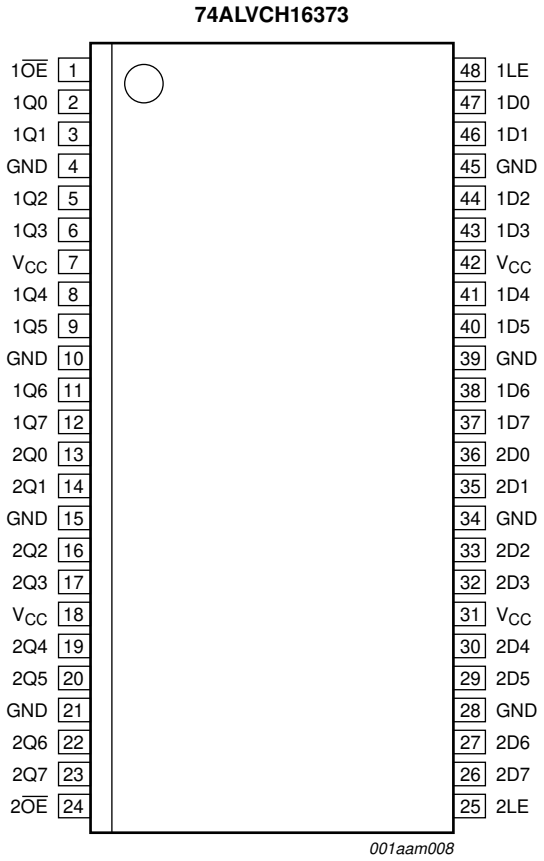


Fig 5. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$1\overline{OE}$, $2\overline{OE}$	1, 24	output enable input (active LOW)
1Q0 to 1Q7	2, 3, 5, 6, 8, 9, 11, 12	data outputs
2Q0 to 2Q7	13, 14, 16, 17, 19, 20, 22, 23	data outputs
GND	4, 10, 15, 21, 28, 34, 39, 45	ground (0 V)
V_{CC}	7, 18, 31, 42	positive supply voltage
1D0 to 1D7	47, 46, 44, 43, 41, 40, 38, 37	data inputs
2D0 to 2D7	36, 35, 33, 32, 30, 29, 27, 26	data inputs
1LE, 2LE	48, 25	latch enable input (active HIGH)

6. Functional description

6.1 Function table

Table 3. Function table[1]

Inputs			Internal latches	Outputs nQn	Operating mode
$n\overline{OE}$	nLE	nDn			
L	H	L	L	L	enable and read register (transparent mode)
L	H	H	H	H	
L	L	l	L	L	latch and read register (hold mode)
L	L	h	H	H	
H	L	l	L	Z	latch register and disable outputs
H	L	h	H	Z	

[1] H = HIGH voltage level;
L = LOW voltage level;
h = HIGH voltage level one set-up time prior to the LOW-to-HIGH LE transition;
l = LOW voltage level one set-up time prior to the LOW-to-HIGH LE transition;
Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CC}	supply voltage			−0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0$ V		−50	-	mA
V_I	input voltage	control inputs	[1]	−0.5	+4.6	V
		data inputs	[1]	−0.5	V_{CC} + 0.5	V
I_{OK}	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V		-	±50	mA
V_O	output voltage		[1]	−0.5	V_{CC} + 0.5	V
I_O	output current	V_O = 0 V to V_{CC}		-	±50	mA
I_{CC}	supply current			-	100	mA
I_{GND}	ground current			−100	-	mA
T_{stg}	storage temperature			−65	+150	°C
P_{tot}	total power dissipation	T_{amb} = −40 °C to +125 °C				
		SSOP48 package	[2]	-	850	mW
		TSSOP48 package	[3]	-	600	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] Above 55 °C the value of P_{tot} derates linearly with 11.3 mW/K.

[3] Above 55 °C the value of P_{tot} derates linearly with 8 mW/K.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage	maximum speed performance				
		C_L = 30 pF	2.3	-	2.7	V
		C_L = 50 pF	3.0	-	3.6	V
		low voltage applications	1.2	-	3.6	V
V_I	input voltage	data inputs	0	-	V_{CC}	V
		control inputs	0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature	in free air	−40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{CC} = 2.3 V to 3.0 V	0	-	20	ns/V
		V_{CC} = 3.0 V to 3.6 V	0	-	10	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
T_{amb} = −40 °C to +85 °C						
V_{IH}	HIGH-level input voltage	V_{CC} = 1.2 V	V_{CC}	-	-	V
		V_{CC} = 1.8 V	$0.7V_{CC}$	0.9	-	V
		V_{CC} = 2.3 V to 2.7 V	1.7	1.2	-	V
		V_{CC} = 2.7 V to 3.6 V	2.0	1.5	-	V
V_{IL}	LOW-level input voltage	V_{CC} = 1.2 V	-	-	0	V
		V_{CC} = 1.8 V	-	0.9	$0.2V_{CC}$	V
		V_{CC} = 2.3 V to 2.7 V	-	1.2	0.7	V
		V_{CC} = 2.7 V to 3.6 V	-	1.5	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I_O = −100 μA; V_{CC} = 1.8 V to 3.6 V	$V_{CC} - 0.2$	V_{CC}	-	V
		I_O = −6 mA; V_{CC} = 1.8 V	$V_{CC} - 0.4$	$V_{CC} - 0.1$	-	V
		I_O = −6 mA; V_{CC} = 2.3 V	$V_{CC} - 0.3$	$V_{CC} - 0.08$	-	V
		I_O = −12 mA; V_{CC} = 2.3 V	$V_{CC} - 0.5$	$V_{CC} - 0.17$	-	V
		I_O = −12 mA; V_{CC} = 2.7 V	$V_{CC} - 0.5$	$V_{CC} - 0.14$	-	V
		I_O = −18 mA; V_{CC} = 2.3 V	$V_{CC} - 0.6$	$V_{CC} - 0.26$	-	V
		I_O = −24 mA; V_{CC} = 3.0 V	$V_{CC} - 1.0$	$V_{CC} - 0.28$	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}				
		I_O = 100 μA; V_{CC} = 1.8 V to 3.6 V	-	0	0.20	V
		I_O = 6 mA; V_{CC} = 1.8 V	-	0.09	0.30	V
		I_O = 6 mA; V_{CC} = 2.3 V	-	0.07	0.20	V
		I_O = 12 mA; V_{CC} = 2.3 V	-	0.15	0.40	V
		I_O = 12 mA; V_{CC} = 2.7 V	-	0.14	0.40	V
		I_O = 18 mA; V_{CC} = 2.3 V	-	0.23	0.60	V
		I_O = 24 mA; V_{CC} = 3.0 V	-	0.27	0.55	V
I_I	input leakage current	V_{CC} = 1.8 V to 3.6 V				
		control input; V_I = 5.5 V or GND	-	0.1	5	μA
		data input; $V_I = V_{CC}$ or GND	-	0.1	5	μA
I_{OZ}	OFF-state output current	$V_I = V_{IH}$ or V_{IL}; $V_O = V_{CC}$ or GND				
		V_{CC} = 1.8 V to 2.7 V	-	0.1	5	μA
		V_{CC} = 2.7 V to 3.6 V	-	0.1	10	μA
I_{LIZ}	OFF-state input leakage current	$V_I = V_{CC}$ or GND				
		V_{CC} = 1.8 V to 2.7 V	-	0.1	10	μA
		V_{CC} = 3.6 V	-	0.1	15	μA
I_{CC}	supply current	$V_I = V_{CC}$ or GND; I_O = 0 A;				
		V_{CC} = 1.8 V to 2.7 V	-	0.2	40	μA
		V_{CC} = 2.7 V to 3.6 V	-	0.2	40	μA

Table 6. Static characteristics *...continued*

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 2.7$ V to 3.6 V					
		per control input		-	5	500	μA
		per data I/O input		-	150	750	μA
I_{BHL}	bus hold LOW current	$V_{CC} = 2.3$ V; $V_I = 0.7$ V	[2]	45	-	-	μA
		$V_{CC} = 3.0$ V; $V_I = 0.8$ V	[2]	75	150	-	μA
I_{BHH}	bus hold HIGH current	$V_{CC} = 2.3$ V; $V_I = 1.7$ V	[2]	−45	-	-	μA
		$V_{CC} = 3.0$ V; $V_I = 2.0$ V	[2]	−75	−175	-	μA
I_{BHLO}	bus hold LOW overdrive current	$V_{CC} = 2.7$ V	[2]	300	-	-	μA
		$V_{CC} = 3.6$ V	[2]	450	-	-	μA
I_{BHHO}	bus hold HIGH overdrive current	$V_{CC} = 2.7$ V	[2]	−300	-	-	μA
		$V_{CC} = 3.6$ V	[2]	−450	-	-	μA
C_I	input capacitance			-	5.0	-	pF

[1] All typical values are measured at $T_{amb} = 25$ °C.

[2] Valid for data inputs of bus hold parts only.

10. Dynamic characteristics

Table 7. Dynamic characteristics

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V); test circuit Figure 10.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
$T_{amb} = -40$ °C to +85 °C							
t_{pd}	propagation delay	nDn to nQn; see Figure 6	[2]				
		$V_{CC} = 1.2$ V		-	8.8	-	ns
		$V_{CC} = 1.8$ V		1.5	3.2	5.7	ns
		$V_{CC} = 2.3$ V to 2.7 V	[3]	1.0	2.1	3.9	ns
		$V_{CC} = 2.7$ V		1.0	2.3	3.7	ns
		$V_{CC} = 3.0$ V to 3.6 V	[4]	1.0	2.1	3.3	ns
		nLE to nQn; see Figure 7	[2]				
		$V_{CC} = 1.2$ V		-	7.4	-	ns
		$V_{CC} = 1.8$ V		1.5	3.4	5.9	ns
		$V_{CC} = 2.3$ V to 2.7 V	[3]	1.0	2.2	3.9	ns
		$V_{CC} = 2.7$ V		1.0	2.2	3.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	[4]	1.0	2.2	3.2	ns
t_{en}	enable time	$\overline{nOE}$ to nQn; see Figure 8	[2]				
		$V_{CC} = 1.2$ V		-	8.9	-	ns
		$V_{CC} = 1.8$ V		1.5	4.0	7.3	ns
		$V_{CC} = 2.3$ V to 2.7 V	[3]	1.0	2.6	5.2	ns
		$V_{CC} = 2.7$ V		1.0	2.9	4.9	ns
		$V_{CC} = 3.0$ V to 3.6 V	[4]	1.0	2.3	4.2	ns

Table 7. Dynamic characteristics *…continued*

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V); test circuit Figure 10.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
t_{dis}	disable time	$n\overline{OE}$ to nQn; see Figure 8	[2]				
		V_{CC} = 1.2 V		-	8.9	-	ns
		V_{CC} = 1.8 V		1.5	3.2	5.6	ns
		V_{CC} = 2.3 V to 2.7 V	[3]	1.0	2.2	4.1	ns
		V_{CC} = 2.7 V		1.0	3.1	4.7	ns
		V_{CC} = 3.0 V to 3.6 V	[4]	1.0	2.8	4.1	ns
t_W	pulse width	nLE HIGH; see Figure 7					
		V_{CC} = 1.8 V		3.5	1.0	-	ns
		V_{CC} = 2.3 V to 2.7 V	[3]	3.0	1.0	-	ns
		V_{CC} = 2.7 V		3.0	1.0	-	ns
		V_{CC} = 3.0 V to 3.6 V	[4]	2.5	1.0	-	ns
t_{su}	set-up time	nDn to nLE; see Figure 9					
		V_{CC} = 1.8 V		1.0	−0.1	-	ns
		V_{CC} = 2.3 V to 2.7 V	[3]	1.0	−0.1	-	ns
		V_{CC} = 2.7 V		1.0	−0.1	-	ns
		V_{CC} = 3.0 V to 3.6 V	[4]	1.0	0.0	-	ns
t_h	hold time	nDn to nLE; see Figure 9					
		V_{CC} = 1.8 V		1.2	0.1	-	ns
		V_{CC} = 2.3 V to 2.7 V	[3]	1.5	0.2	-	ns
		V_{CC} = 2.7 V		1.5	0.4	-	ns
		V_{CC} = 3.0 V to 3.6 V	[4]	1.2	0.2	-	ns
C_{PD}	power dissipation capacitance	per flip-flop; V_I = GND to V_{CC}	[5]				
		outputs enabled		-	16	-	pF
		outputs disabled		-	10	-	pF

[1] All typical values are measured at T_{amb} = 25 °C.

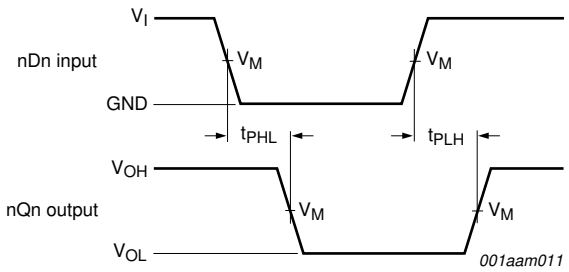
[2] t_{pd} is the same as t_{PLH} and t_{PHL}.
t_{en} is the same as t_{PZL} and t_{PZH}.
t_{dis} is the same as t_{PLZ} and t_{PHZ}.

[3] Typical values are measured at V_{CC} = 2.5 V.

[4] Typical values are measured at V_{CC} = 3.3 V.

[5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
f_i = input frequency in MHz; f_o = output frequency in MHz;
C_L = output load capacitance in pF;
V_{CC} = supply voltage in Volts;
N = number of inputs switching;
$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

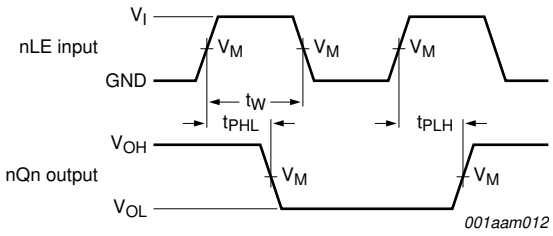
11. Waveforms



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical output levels that occur with the output load.

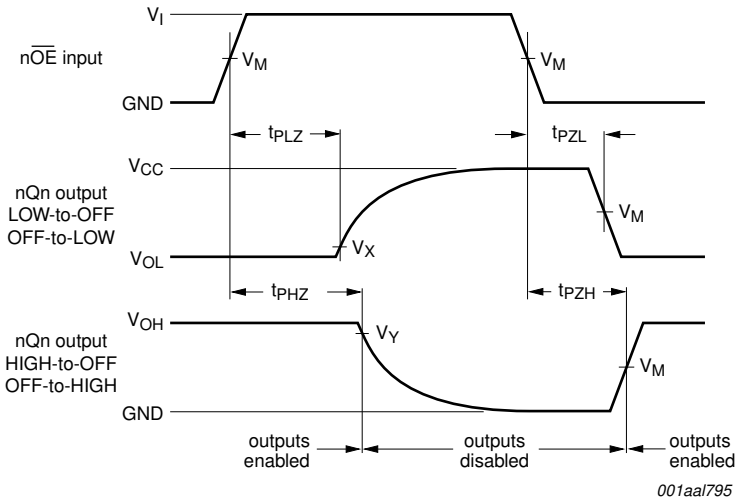
Fig 6. Propagation delay, input (nDn) to data output (nQn)



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical output levels that occur with the output load.

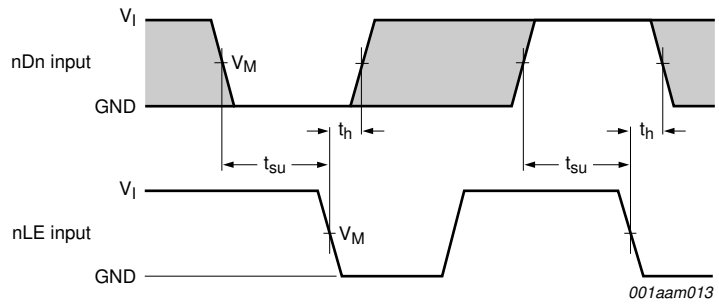
Fig 7. Propagation delay, latch enable input (nLE) to data output (nQn), and pulse width



Measurement points are given in Table 8.

V_{OL} and V_{OH} are typical output levels that occur with the output load.

Fig 8. 3-state enable and disable times



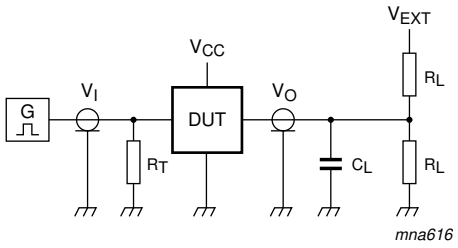
The shaded areas indicate when the input is permitted to change for predictable output performance.

Fig 9. Data setup and hold times for input (nDn) to input (nLE)

Table 8. Measurement points

Supply voltage	Input		Output		
V_{CC}	V_I	V_M	V_M	V_X	V_Y
2.3 V to 2.7 V and < 2.3 V	V_{CC}	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	V_{OL} + 0.15 V	V_{OH} − 0.15 V
2.7 V	2.7 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V
3.0 V to 3.6 V	2.7 V	1.5 V	1.5 V	V_{OL} + 0.3 V	V_{OH} − 0.3 V

12. Test information



Test data is given in Table 9.

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

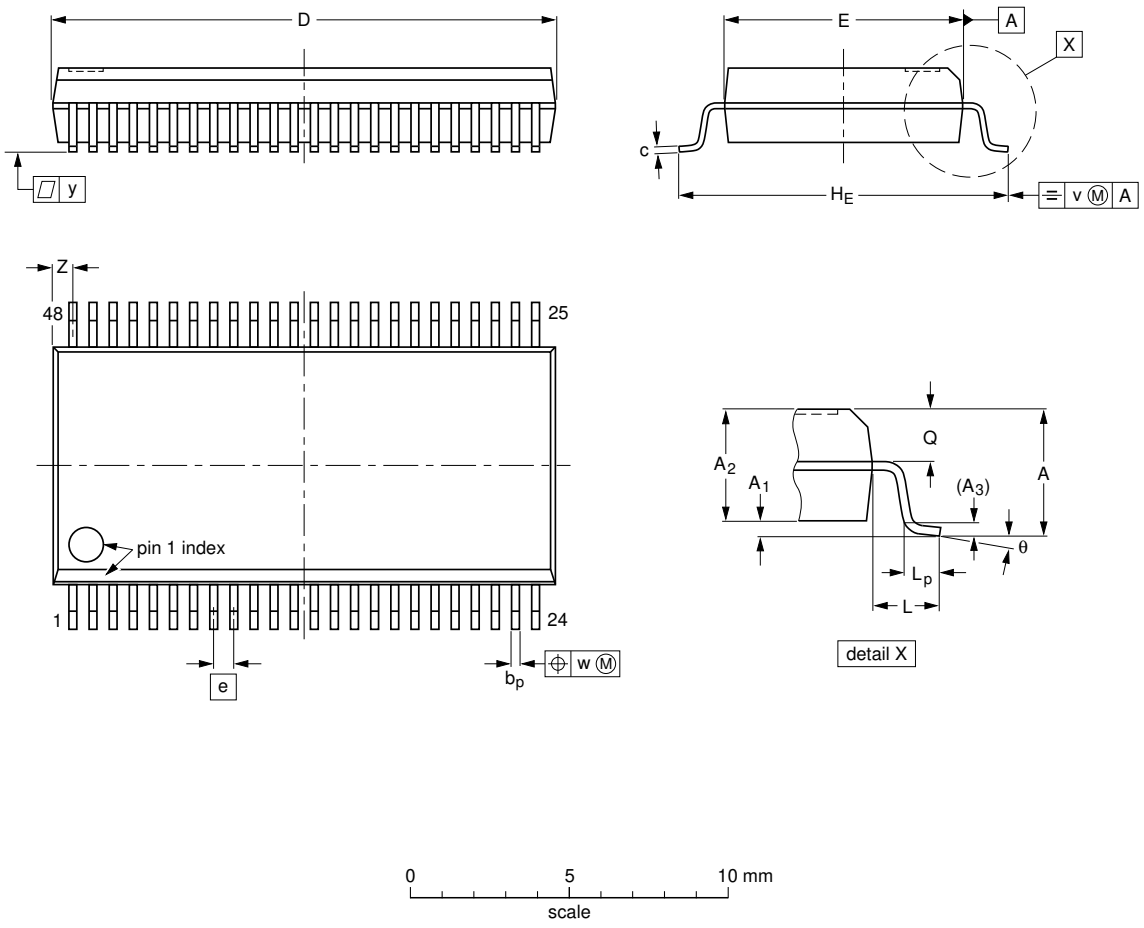
Fig 10. Load circuit for measuring switching times

Table 9. Test data

Supply voltage	Input		Load		V_{EXT}		
V_{CC}	V_I	t_r, t_f	C_L	R_L	t_{PLH}, t_{PHL}	t_{PLZ}, t_{PZL}	t_{PHZ}, t_{PZH}
2.3 V to 2.7 V and < 2.3 V	V_{CC}	≤ 2.0 ns	30 pF	500 Ω	open	2 × V_{CC}	GND
2.7 V	2.7 V	2.5 ns	50 pF	500 Ω	open	2 × V_{CC}	GND
3.0 V to 3.6 V	2.7 V	2.5 ns	50 pF	500 Ω	open	2 × V_{CC}	GND

13. Package outline

SSOP48: plastic shrink small outline package; 48 leads; body width 7.5 mm **SOT370-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (1)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	2.8	0.4 0.2	2.35 2.20	0.25	0.3 0.2	0.22 0.13	16.00 15.75	7.6 7.4	0.635	10.4 10.1	1.4	1.0 0.6	1.2 1.0	0.25	0.18	0.1	0.85 0.40	8° 0°

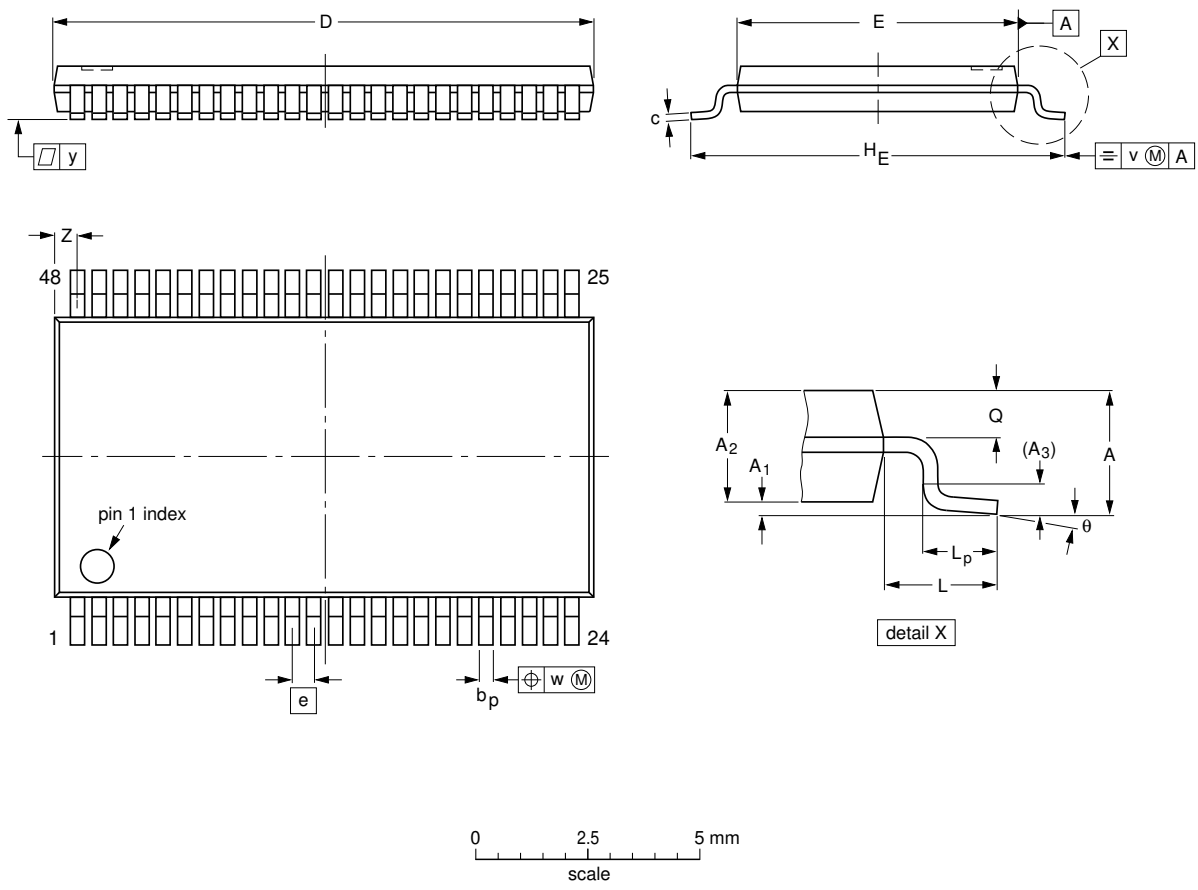
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT370-1		MO-118				~~99-12-27~~ 03-02-19

Fig 11. Package outline SOT370-1 (SSOP48)

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm **SOT362-1**



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	12.6 12.4	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.8 0.4	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT362-1		MO-153				~~99-12-27~~ 03-02-19

Fig 12. Package outline SOT362-1 (TSSOP48)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVCH16373 v.6	20120710	Product data sheet	-	74ALVCH16373 v.5
Modifications:	• Table 8 corrected (errata).			
74ALVCH16373 v.5	20111117	Product data sheet	-	74ALVCH16373 v.4
Modifications:	• Legal pages updated.			
74ALVCH16373 v.4	20100531	Product data sheet	-	74ALVCH16373 v.3
74ALVCH16373 v.3	19990920	Product specification	-	74ALVCH16373 v.2
74ALVCH16373 v.2	19980629	Product specification	-	74ALVCH16373 v.1
74ALVCH16373 v.1	19970321	Product specification	-	-

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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